

LUMAWISE | Inverted Thru-Board

TE Internal #: 2213189-4

Inverted Thru-Board, PCB Mount Receptacle, Vertical, Wire-to-Board, 2 Position, 3.3mm [.129in] Centerline, 1 Row, Tin, Natural

Housing Color

View on TE.com >



Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Headers & Receptacles









PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical
Connector System: Wire-to-Board

Number of Positions: 2

Centerline (Pitch): 3.3 mm [.129 in]

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Receptacle |
|-----------------------------------|-----------------------|
| Connector System | Wire-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| PCB Mount Orientation | Vertical |
| Number of Positions | 2 |
| Number of Rows | 1 |
| Electrical Characteristics | |
| Operating Voltage | 400 VAC |
| Contact Footures | |

Contact Features

| Contact Layout | Inline |
|---|------------------|
| Contact Retention Within Housing | With |
| Contact Fabrication | Stamped & Formed |
| PCB Contact Termination Area Plating Material Thickness | 2 μm[78.74 μin] |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Underplating Material | Nickel |
| | |



| PCB Contact Termination Area Plating Material | Tin-Lead |
|--|----------------------------|
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Tin |
| Contact Mating Area Plating Material Finish | Matte |
| Contact Mating Area Plating Material Thickness | 2 μm[78.74 μin] |
| Contact Current Rating (Max) | 2 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .3 mm[.012 in] |
| Rectangular Termination Post & Tail Width | 2.5 mm[.098 in] |
| Termination Method to Wire & Cable | Poke-In |
| Termination Method to Printed Circuit Board | Surface Mount |
| Mechanical Attachment | |
| Strain Relief | Without |
| Mating Alignment Type | Polarization |
| Mating Alignment | With |
| Contact Retention Type Within Housing | Locking Lance |
| PCB Mount Retention Type | Boardlock |
| PCB Mount Alignment | Without |
| Mating Retention | Without |
| PCB Mount Retention | With |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Mating Entry Location | Bottom |
| Centerline (Pitch) | 3.3 mm[.129 in] |
| Housing Color | Natural |
| Housing Material | Thermoplastic |
| Dimensions | |
| Connector Length | 8.3 mm[.327 in] |
| Connector Height | 10.6 mm[.417 in] |
| Connector Width | 11.3 mm[.445 in] |
| Usage Conditions | |
| Operating Temperature Range | -40 – 130 °C[-40 – 266 °F] |



Operation/Application

| Circuit Application | Power |
|--|--------------------------------|
| Industry Standards | |
| Glow Wire Rating | Standard Part - Not Glow Wire |
| UL Flammability Rating | UL 94V-0 |
| Agency/Standard | CSA, UL |
| Agency/Standard Number | C22.2 No. 182.3-M1987, UL 1977 |
| | |
| UL File Number | E28476 |
| UL File Number Packaging Features | E28476 |
| | E28476 350 |
| Packaging Features | |
| Packaging Features Packaging Quantity | 350 |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|--|
| EU ELV Directive 2000/53/EC | Not Yet Reviewed |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JUN 2018 (191) SVHC > Threshold: Not Yet Reviewed |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on

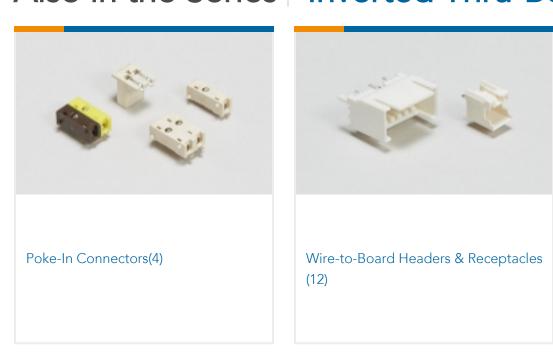


requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

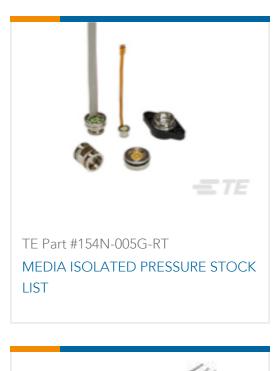
Compatible Parts



Also in the Series | Inverted Thru-Board



Customers Also Bought

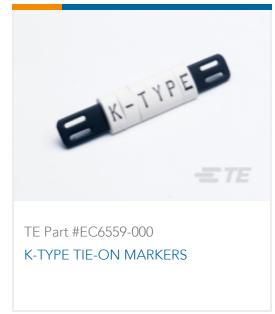






















Documents

Product Drawings

Assembly, IPI Connector 26-24GA w cap

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2213189-4_3_c-2213189-4-3.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2213189-4_3_c-2213189-4-3.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2213189-4_3_c-2213189-4-3.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

Inverted Card Edge & Poke In Connector Brochure

English

Inverted Thru Board Interconnects

English

Inverted Thru Board Interconnects

Product Specifications

Application Specification

English

Agency Approvals

Inverted Thru Board Connectors to IEC 60998

English

Inverted Thru Board Connectors to IEC 60998

English